WHAT IS CLAIMED IS:

1. A display apparatus, comprising:

an insulating substrate;

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a signal line for transmitting a signal to a pixel formed in a display area composed of pixels on the insulating substrate;

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a driver integrated circuit (IC) mounted outside of the display area of the insulating substrate and electrically connected to the signal line; and

an inspection pad formed outside of the display area of the insulating substrate, electrically connected to the signal line, and covered with resin.

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2. A display apparatus according to Claim 1, wherein the resin is selected from the group consisting of silicon, acryl, urethane, epoxy, and polyimide.

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- 3. A display apparatus according to Claim 1, wherein the resin is an anisotropic conductive film.
- 25 further comprising:

a signal input pad formed outside of the display

A display apparatus according to Claim 1,

area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC,

wherein the signal input pad and the inspection pad are covered with an anisotropic conductive film.

- 5. A display apparatus according to Claim 1, further comprising:
- a conductive extension line connecting the signal line and the driver IC to the inspection pad.

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- 6. A display apparatus according to Claim 2, further comprising:
- a conductive extension line connecting the signal line and the driver IC to the inspection pad.
 - 7. A display apparatus according to Claim 3, further comprising:
- a conductive extension line connecting the signal line and the driver IC to the inspection pad.
 - 8. A display apparatus according to Claim 4, further comprising:
 - a conductive extension line connecting the signal line and the driver IC to the inspection pad.

9. A display apparatus according to Claim 4, further comprising:

a wiring substrate for inputting a signal from outside of the insulating substrate to the driver IC,

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wherein the wiring substrate and the signal input pad on the insulating substrate are electrically connected by the anisotropic conductive film, and

the wiring substrate covers the signal input pad and the inspection pad with the anisotropic conductive film interposed therebetween.

- 10. A display apparatus according to Claim 9, wherein the wiring substrate is a flexible substrate.
- 11. A display apparatus according to Claim 4, wherein the inspection pad and the signal input pad are substantially aligned along near an edge of the insulating substrate.

12. A method of manufacturing a display apparatus, comprising steps of:

forming a signal line for transmitting a signal to a pixel formed in a display area on the insulating substrate;

implementing a driver integrated circuit (IC)

outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

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forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.

13. A method of manufacturing a display apparatus, comprising steps of:

forming a signal line for transmitting a signal to a pixel formed in a display area on the insulating substrate;

implementing a driver integrated circuit (IC) outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an IC signal pad at a position corresponding to a pad formed on the driver IC on the insulating substrate;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

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simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.